



Advance Product Change Notification

202010043A

Issue Date: 19-Nov-2020



Change Category

- | | | | | |
|--|---|---|---|---|
| ☐ Wafer Fab Process | ☒ Assembly Process | ☒ Product Marking | ☐ Test Location | ☐ Design |
| ☐ Wafer Fab Materials | ☐ Assembly Materials | ☐ Mechanical Specification | ☐ Test Process | ☐ Errata |
| ☐ Wafer Fab Location | ☐ Assembly Location | ☐ Packing/Shipping/Labeling | ☐ Test Equipment | ☐ Electrical spec./Test coverage |
| ☐ Firmware | ☒ Other - Planned Part Number Replacement | | | |

i.MX53 PBGA Product Molding Change from Corner-Gate Mold(CGM) to Pin-Gate Mold(PGM)

Description of Change

This Advanced Notification is to announce the planned conversion from Corner-Gate Mold (CGM) process platform to Pin-Gate Mold (PGM) process platform for the devices listed in this notification.

The change from Corner-Gate Mold (CGM) process to Pin-Gate Mold (PGM) process is driven by NXP assembly subcontractor Amkor Korea announcing it will phase out CGM (Corner-Gate mold) PBGA assembly platform by late June 2021, and production support will be continued with PGM (Pin-Gate mold) PBGA process thereafter. CGM PBGA process platform capacity has been contracting due to the transition to PGM process platform.

To support the transition to Pin-Gate Mold (PGM) process, a Discontinuance Notification will be issued (planned issuance April 2021) with new replacement part numbers and qualification results for Pin-Gate Mold (PGM) process. New replacement part numbers are required as devices will have a new case outline. Note: There are no dimensional changes to the package; new case outline is required due to change of physical

appearance and part marking format only.

Due to the timing of the transition from Corner-Gate Mold (CGM) process to Pin-Gate Mold (PGM), the planned discontinuance notice will have accelerated last order dates. Customer's may choose to qualify new replacement part numbers using Pin-Gate Mold (PGM) or may choose to place life time buys for existing part numbers.

Please refer to attachment for the detailed changes and planned replacement part numbers that will be included in the planned discontinuance notification.

Reason for Change

Assembly subcontractor Amkor converting from Corner-Gate Mold (CGM) process to Pin-Gate Mold (PGM) process. Pin-Gate Mold (PGM) process to be qualified as assurance of supply.

Identification of Affected Products

Replacement part type created, see Parts Affected list

New replacement part numbers will be listed in planned Discontinuance Notification.

Note: Package identifier will change in the orderable part number (i.e. "VV" will be replaced by "VP").

Product Availability

Sample Information

Samples are available from 28-Dec-2020

Prototype sample part numbers will be made available prior to planned Discontinuance Notification:

PCIMX535DVP1C2

PCIMX537CVP8C2

PCIMX535DVP2C2

Production

Planned first shipment 26-Jul-2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

The Self Qualification Report will be ready on 22-Apr-2021.

The Final PCN is planned to be issued on: 30-Apr-2021.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Dec-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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